

DB6J316K

Silicon epitaxial planar type

For small current rectification
DB2S316 in SMini6 type package

■ Features

- Short reverse recovery time t_{rr}
- Low forward voltage V_F
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Basic Part Number

Triple DB2S316 (Parallel)

■ Packaging

DB6J316K0R Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

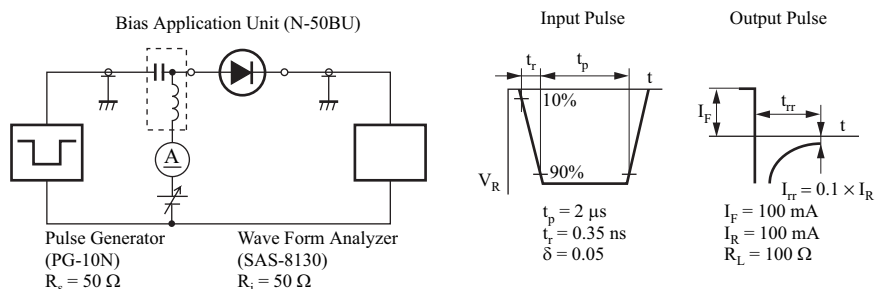
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			15	μA
Terminal capacitance	C_t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R,$ $R_L = 100 \Omega$		0.8		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

*: t_{rr} measurement circuit



■ Package

• Code

SMini6-F3-B

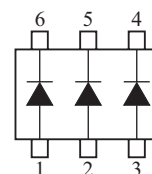
Package dimension clicks here.→

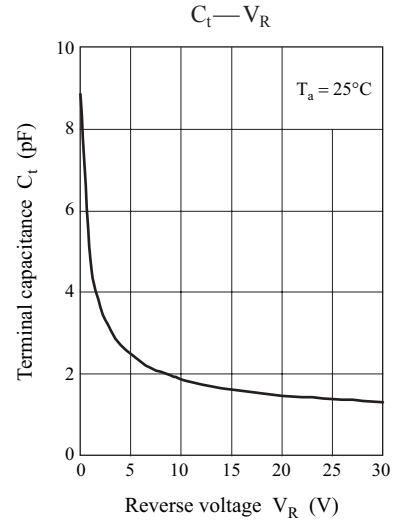
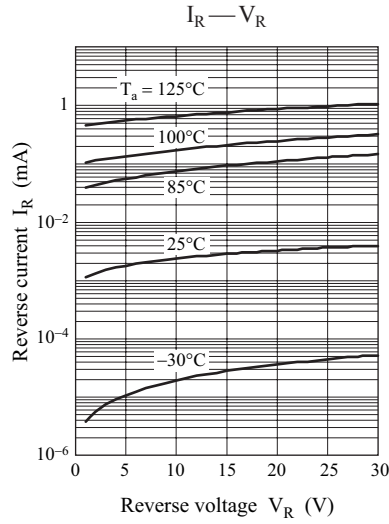
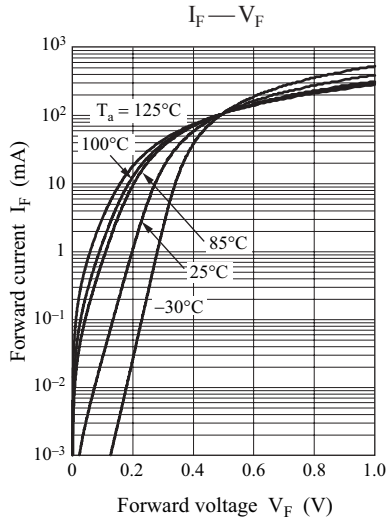
• Pin Name

- | | |
|-------------|--------------|
| 1: Anode-1 | 4: Cathode-3 |
| 2: Anode-2. | 5: Cathode-2 |
| 3: Anode-3 | 6: Cathode-1 |

■ Marking Symbol: 5E

■ Internal Connection





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